

Low Voltage Automotive Fast 128K x 8 SRAM

Features

- 131072 x 8 bit static CMOS RAM
- 35 and 55 ns Access Time
- Common data inputs and data outputs
- Three-state outputs
- Typ. operating supply current
35 ns: 45mA
55 ns: 30mA
- Standby current <100µA at 125°C
- TTL/CMOS-compatible
- Power supply voltage 3.3 V
- Operating temperature range
-40 °C to 85 °C
-40 °C to 125 °C
- CECC 90000 Quality Standard
- ESD protection > 2000 V
(MIL STD 883C M3015.7)
- Latch-up immunity >100 mA
- Package: SOP32 (300/330 mil)

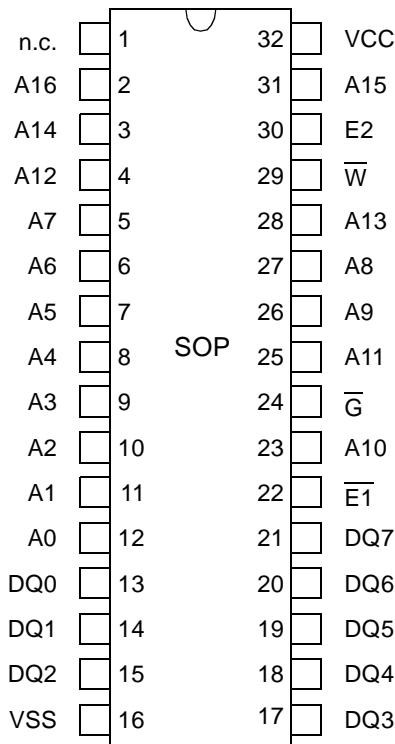
Description

The UL62H1708A is a static RAM manufactured using a CMOS process technology with the following operating modes:

| | |
|---------|------------------|
| - Read | - Standby |
| - Write | - Data Retention |

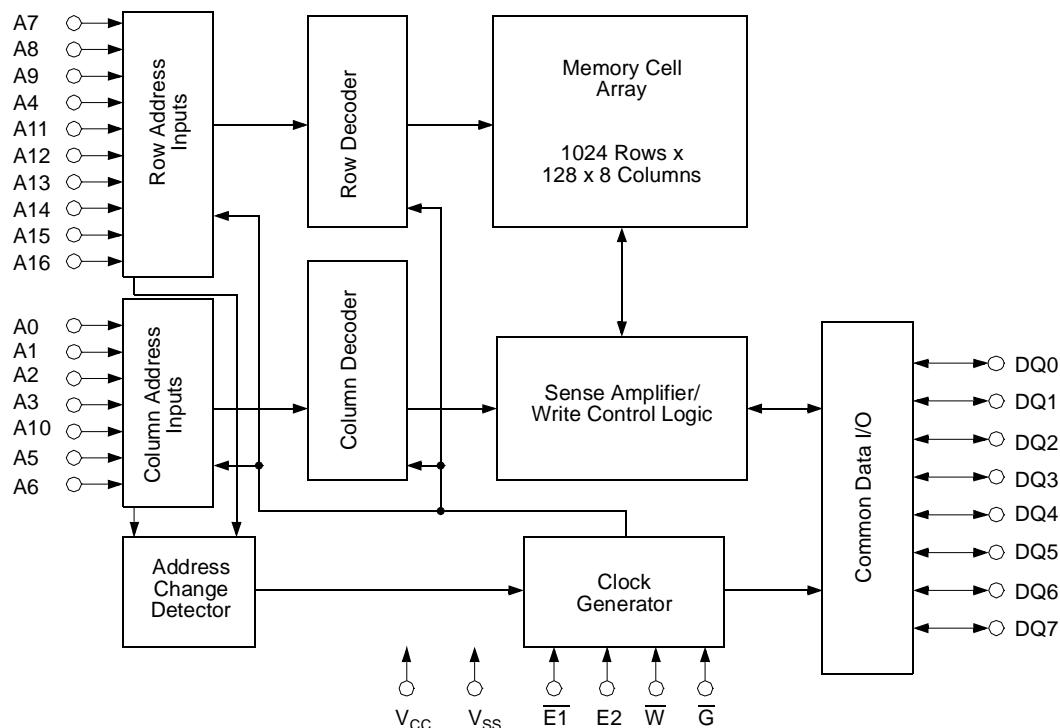
The memory array is based on a 6-Transistor cell. The circuit is activated by the rising edge of E2 (at $E1 = L$), or the falling edge of $\bar{E}1$ (at $E2 = H$). The address and control inputs open simultaneously. According to the information of W and G, the data inputs, or outputs, are active. During the active state ($\bar{E}1 = L$ and $E2 = H$) each address change leads to a new Read or Write cycle. In a Read cycle, the data outputs are activated by the falling edge of G, afterwards the data word will be available at the outputs DQ0-DQ7. After the address change, the data

outputs go High-Z until the new information is available. The data outputs have no preferred state. If the memory is driven by CMOS levels in the active state, and if there is no change of the address, data input and control signals W or G, the operating current ($I_o = 0$ mA) drops to the value of the operating current in the Standby mode. The Read cycle is finished by the falling edge of E2 or \bar{W} , or by the rising edge of $\bar{E}1$, respectively. Data retention is guaranteed down to 2 V. With the exception of $\bar{E}1$ and E2, all inputs consist of NOR gates, so that no pull-up/pull-down resistors are required.

Pin Configuration**Pin Description**

Top View

| Signal Name | Signal Description |
|-------------|----------------------|
| A0 - A16 | Address Inputs |
| DQ0 - DQ7 | Data In/Out |
| $\bar{E}1$ | Chip Enable 1 |
| E2 | Chip Enable 2 |
| \bar{G} | Output Enable |
| \bar{W} | Write Enable |
| VCC | Power Supply Voltage |
| VSS | Ground |
| n.c. | not connected |

Block Diagram**Truth Table**

| Operating Mode | $\overline{E1}$ | $E2$ | \overline{W} | \overline{G} | DQ0 - DQ7 |
|----------------------|-----------------|------|----------------|----------------|--------------------|
| Standby/not selected | * | L | * | * | High-Z |
| | H | * | * | * | High-Z |
| Internal Read | L | H | H | H | High-Z |
| Read | L | H | H | L | Data Outputs Low-Z |
| Write | L | H | L | * | Data Inputs High-Z |

* H or L

CharacteristicsAll voltages are referenced to $V_{SS} = 0$ V (ground).

All characteristics are valid in the power supply voltage range and in the operating temperature range specified.

Dynamic measurements are based on a rise and fall time of ≤ 5 ns, measured between 10 % and 90 % of V_I , as well as input levels of $V_{IL} = 0$ V and $V_{IH} = 2.5$ V. The timing reference level of all input and output signals is 1.5 V, with the exception of the t_{dis} -times and t_{en} -times, in which cases transition is measured ± 200 mV from steady-state voltage.

| Maximum Ratings | | Symbol | Min. | Max. | Unit |
|---|------------------|------------|------------|----------------|------|
| Power Supply Voltage | | V_{CC} | -0.3 | 4.6 | V |
| Input Voltage | | V_I | -0.5 | $V_{CC} + 0.5$ | V |
| Output Voltage | | V_O | -0.5 | $V_{CC} + 0.5$ | V |
| Power Dissipation | | P_D | - | 1 | W |
| Operating Temperature | K-Type A-Type | T_a | -40 -40 | 85 125 | °C |
| Storage Temperature | | T_{stg} | -65 | 150 | °C |
| Output Short-Circuit Current at $V_{CC} = 3.3$ V and $V_O = 0$ V** | | $ I_{os} $ | | 100 | mA |

** Not more than 1 output should be shorted at the same time. Duration of the short circuit should not exceed 30 s.

| Recommended Operating Conditions | Symbol | Conditions | Min. | Max. | Unit |
|----------------------------------|----------|------------|------|----------------|------|
| Power Supply Voltage | V_{CC} | | 3.0 | 3.6 | V |
| Input Low Voltage* | V_{IL} | | -0.3 | 0.8 | V |
| Input High Voltage | V_{IH} | | 2.0 | $V_{CC} + 0.3$ | V |

* -2 V at Pulse Width 10 ns

| Electrical Characteristics | Symbol | Conditions | Min. | Max. | Unit |
|---|---------------|--|------|----------------|----------------|
| Supply Current - Operating Mode | $I_{CC(OP)}$ | $V_{CC} = 3.6 \text{ V}$ $V_{IL} = 0.8 \text{ V}$ $V_{IH} = 2.0 \text{ V}$ $t_{CW} = 35 \text{ ns}$ $t_{CW} = 55 \text{ ns}$ $t_{CW} = 70 \text{ ns}$ | | 90 70 60 | mA mA mA |
| Supply Current - Standby Mode (CMOS level) | $I_{CC(SB)}$ | $V_{CC} = 3.6 \text{ V}$ $V_{E1} = V_{E2} = V_{CC} - 0.2 \text{ V}$ | | 100 | μA |
| Supply Current - Standby Mode (TTL level) | $I_{CC(SB)1}$ | $V_{CC} = 3.6 \text{ V}$ $V_{E1} = V_{E2} = 2.0 \text{ V}$ K-Type A-Type | | 10 20 | mA mA |
| Output High Voltage | V_{OH} | $V_{CC} = 3.0 \text{ V}$ $I_{OH} = -0.5 \text{ mA}$ | 2.2 | | V |
| Output Low Voltage | V_{OL} | $V_{CC} = 3.0 \text{ V}$ $I_{OL} = 0.5 \text{ mA}$ | | 0.4 | V |
| Input High Leakage Current | I_{IH} | $V_{CC} = 3.6 \text{ V}$ $V_{IH} = 3.6 \text{ V}$ | | 2 | μA |
| Input Low Leakage Current | I_{IL} | $V_{CC} = 3.6 \text{ V}$ $V_{IL} = 0 \text{ V}$ | -2 | | μA |
| Output High Current | I_{OH} | $V_{CC} = 3.0 \text{ V}$ $V_{OH} = 2.0 \text{ V}$ | | -0.5 | mA |
| Output Low Current | I_{OL} | $V_{CC} = 3.0 \text{ V}$ $V_{OL} = 0.4 \text{ V}$ | 0.5 | | mA |
| Output Leakage Current High at Three-State Outputs | I_{OHZ} | $V_{CC} = 3.6 \text{ V}$ $V_{OH} = 3.6 \text{ V}$ | | 2 | μA |
| Low at Three-State Outputs | I_{OLZ} | $V_{CC} = 3.6 \text{ V}$ $V_{OL} = 0 \text{ V}$ | -2 | | μA |

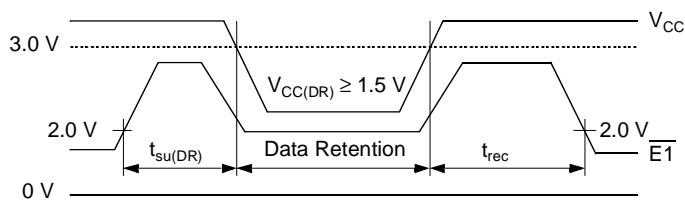
| Switching Characteristics Read Cycle | Symbol | | 35 | | 55 | | Unit |
|---|---------------|--------------|-------------|-------------|-------------|-------------|-------------|
| | Alt. | IEC | Min. | Max. | Min. | Max. | |
| Read Cycle Time | t_{RC} | t_{cR} | 35 | | 55 | | ns |
| Address Access Time to Data Valid | t_{AA} | $t_{a(A)}$ | | 35 | | 55 | ns |
| Chip Enable Access Time to Data Valid | t_{ACE} | $t_{a(E)}$ | | 35 | | 55 | ns |
| \bar{G} LOW to Data Valid | t_{OE} | $t_{a(G)}$ | | 15 | | 25 | ns |
| \bar{E}_1 HIGH or E_2 LOW to Output in High-Z | t_{HZCE} | $t_{dis(E)}$ | | 12 | | 15 | ns |
| \bar{G} HIGH to Output in High-Z | t_{HZOE} | $t_{dis(G)}$ | | 12 | | 15 | ns |
| \bar{E}_1 LOW or E_2 HIGH to Output in Low-Z | t_{LZCE} | $t_{en(E)}$ | 3 | | 3 | | ns |
| \bar{G} LOW to Output in Low-Z | t_{LZOE} | $t_{en(G)}$ | 0 | | 0 | | ns |
| Output Hold Time from Address Change | t_{OH} | $t_{v(A)}$ | 3 | | 3 | | ns |
| \bar{E}_1 LOW or E_2 HIGH to Power-Up Time | t_{PU} | | 0 | | 0 | | ns |
| \bar{E}_1 HIGH or E_2 LOW to Power-Down Time | t_{PD} | | | 35 | | 55 | ns |

| Switching Characteristics Write Cycle | Symbol | | 35 | | 55 | | Unit |
|--|---------------|----------------|-------------|-------------|-------------|-------------|-------------|
| | Alt. | IEC | Min. | Max. | Min. | Max. | |
| Write Cycle Time | t_{WC} | t_{cW} | 35 | | 55 | | ns |
| Write Pulse Width | t_{WP} | $t_{w(W)}$ | 20 | | 35 | | ns |
| Write Setup Time | t_{WP} | $t_{su(W)}$ | 20 | | 35 | | ns |
| Address Setup Time | t_{AS} | $t_{su(A)}$ | 0 | | 0 | | ns |
| Address Valid to End of Write | t_{AW} | $t_{su(A-WH)}$ | 20 | | 40 | | ns |
| Chip Enable Setup Time | t_{CW} | $t_{su(E)}$ | 25 | | 40 | | ns |
| Pulse Width Chip Enable to End of Write | t_{CW} | $t_{w(E)}$ | 25 | | 40 | | ns |
| Data Setup Time | t_{DS} | $t_{su(D)}$ | 15 | | 25 | | ns |
| Data Hold Time | t_{DH} | $t_{h(D)}$ | 0 | | 0 | | ns |
| Address Hold from End of Write | t_{AH} | $t_{h(A)}$ | 0 | | 0 | | ns |
| \bar{W} LOW to Output in High-Z | t_{HZWE} | $t_{dis(W)}$ | | 15 | | 20 | ns |
| \bar{G} HIGH to Output in High-Z | t_{HZOE} | $t_{dis(G)}$ | | 12 | | 15 | ns |
| \bar{W} HIGH to Output in Low-Z | t_{LZWE} | $t_{en(W)}$ | 0 | | 0 | | ns |
| \bar{G} LOW to Output in Low-Z | t_{LZOE} | $t_{en(G)}$ | 0 | | 0 | | ns |

Data Retention Mode

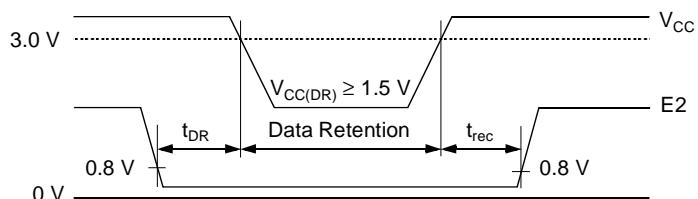
| Data Retention Characteristics | Symbol | | Conditions | Min. | Typ. | Max. | Unit |
|--------------------------------|-----------|--------------|--|----------|------|------|---------------|
| | Alt. | IEC | | | | | |
| Data Retention Supply Voltage | | $V_{CC(DR)}$ | | 1.5 | | 3.6 | V |
| Data Retention Supply Current | | $I_{CC(DR)}$ | $V_{CC(DR)} = 2\text{ V}$ $V_{E1} = V_{E2} = V_{CC(DR)} - 0.2\text{ V}$ | | | 30 | μA |
| Data Retention Setup Time | t_{CDR} | $t_{su(DR)}$ | See Data Retention Waveforms (below) | 0 | | | ns |
| Operating Recovery Time | t_R | t_{rec} | | t_{cR} | | | ns |

Data Retention Mode E1 - controlled



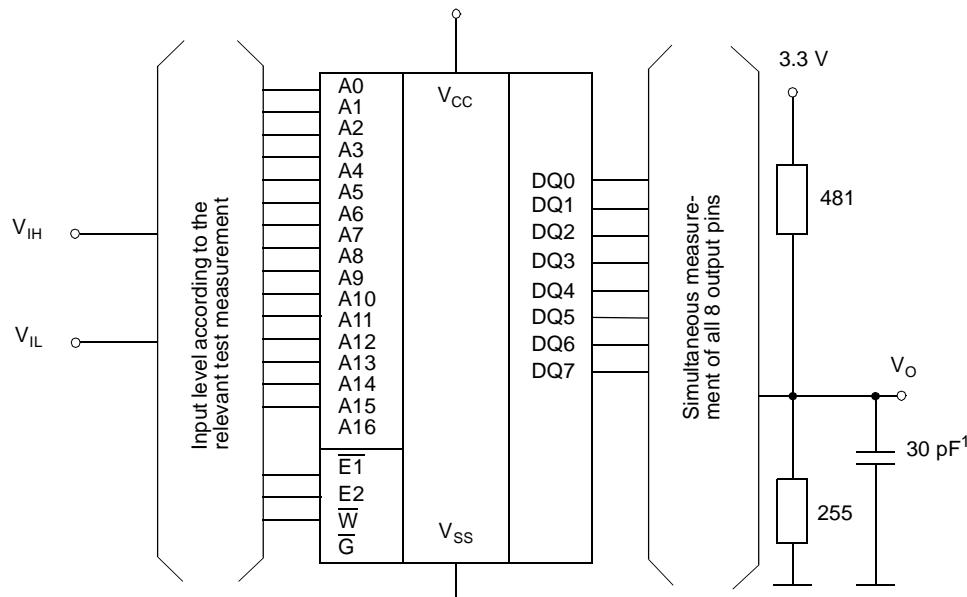
$$\begin{aligned} V_{E2(DR)} &\geq V_{CC(DR)} - 0.2\text{ V} \text{ or } V_{E2(DR)} \leq 0.2\text{ V} \\ V_{CC(DR)} - 0.2\text{ V} &\leq V_{E1(DR)} \leq V_{CC(DR)} + 0.2\text{ V} \end{aligned}$$

Data Retention Mode E2 - controlled



$$\begin{aligned} V_{E1(DR)} &\geq V_{CC(DR)} - 0.2\text{ V} \text{ or } V_{E1(DR)} \leq 0.2\text{ V} \\ V_{E2(DR)} &\leq 0.2\text{ V} \end{aligned}$$

Test Configuration for Functional Check

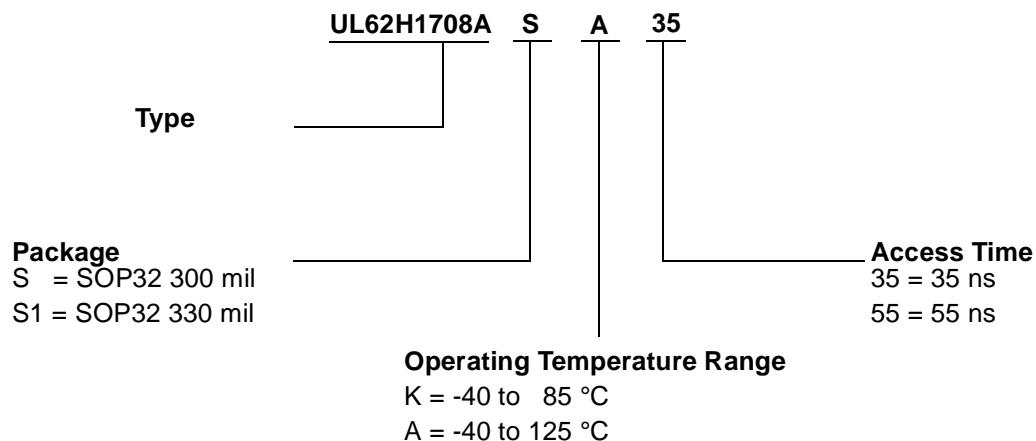


1) In measurement of $t_{dis(E)}$, $t_{dis(W)}$, $t_{en(E)}$, $t_{en(W)}$, $t_{en(G)}$ the capacitance is 5 pF.

| Capacitance | Conditions | Symbol | Min. | Max. | Unit |
|--------------------|--|--------|------|------|------|
| Input Capacitance | $V_{CC} = 3.3 \text{ V}$ $V_I = V_{SS}$ $f = 1 \text{ MHz}$ $T_a = 25^\circ \text{C}$ | C_I | | 7 | pF |
| Output Capacitance | | C_o | | 7 | pF |

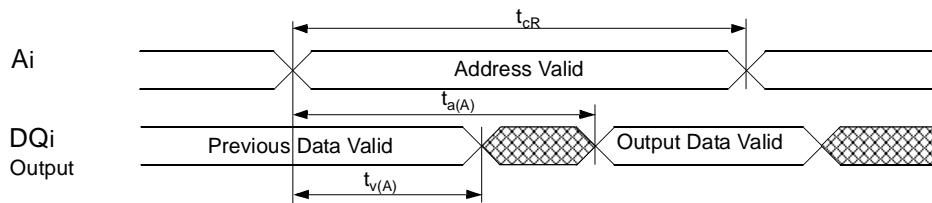
All pins not under test must be connected with ground by capacitors.

IC Code Numbers

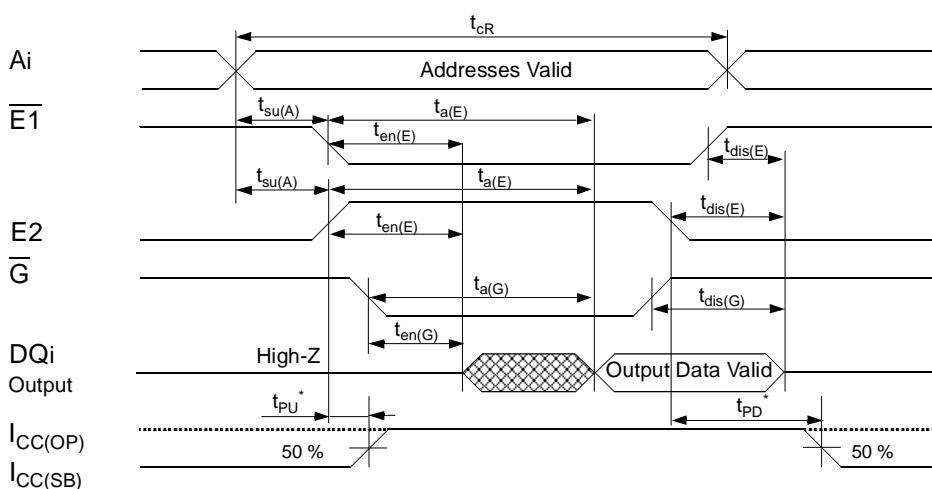


The date of manufacture is given by the last 4 digits of the mark, the first 2 digits indicating the year, and the last 2 digits the calendar week.

Read Cycle 1: A_i -controlled (during Read Cycle : $\overline{E1} = \overline{G} = V_{IL}$, $\overline{W} = E2 = V_{IH}$)

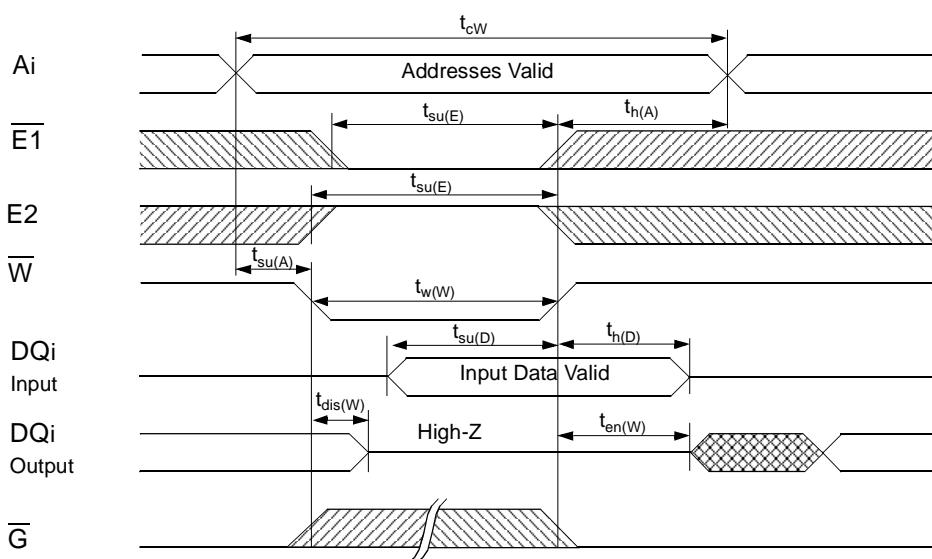


Read Cycle 2: \overline{G} , $\overline{E1}$, $E2$ -controlled (during Read Cycle: $\overline{W} = V_{IH}$)

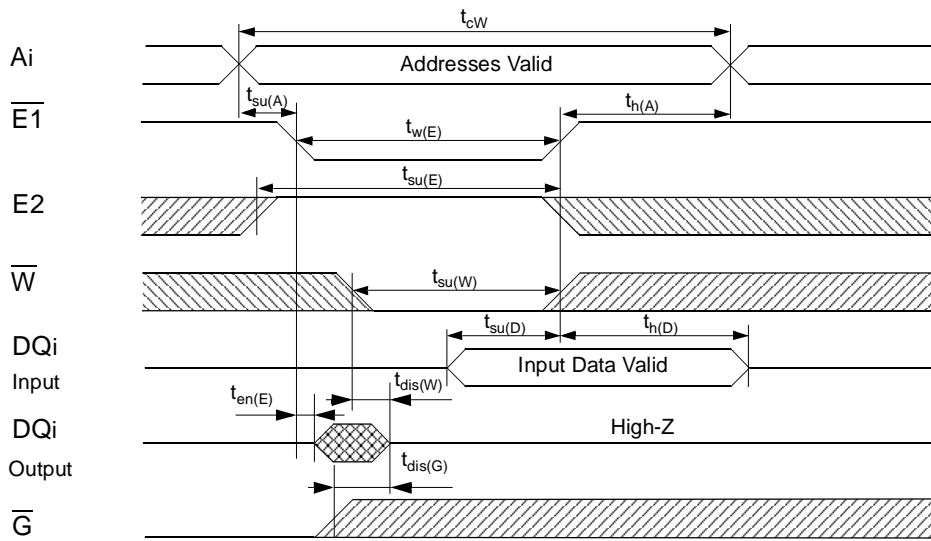


* The same applies to $\overline{E1}$

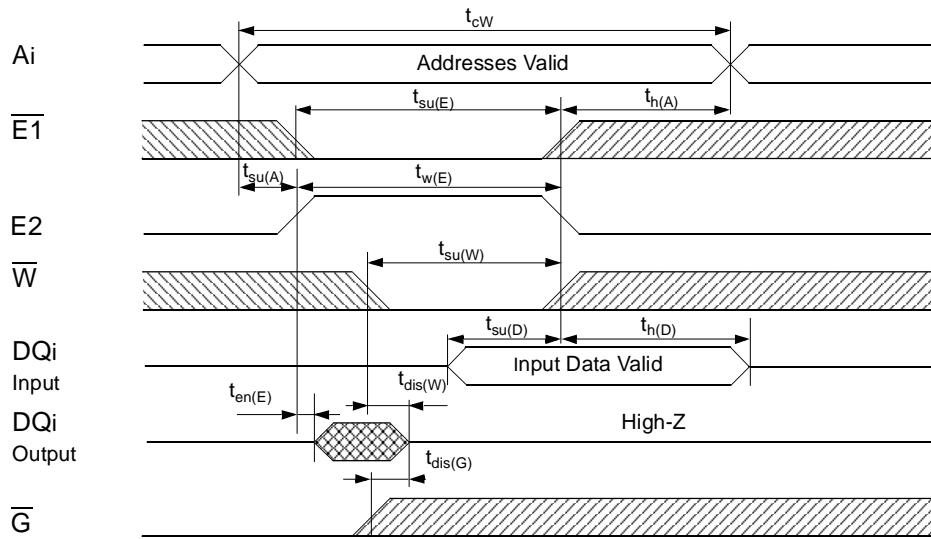
Write Cycle1: \overline{W} -controlled



Write Cycle 2: E1-controlled



Write Cycle 3 (E2-controlled)



undefined L- to H-level H- to L-level

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